

Build up for Mindteck
mind-16june2k11-11762

0.0325	Copper plating layer 1		
0.0175	Copper foil layer 1	Signal	6.5 mil trace width, 56.26 ohms single ended Target 50 ohms 5 mil trace width, 6.8 mil seperation, 103.74 ohms differential Target 100 ohms 6 mil trace width, 5.8 mil seperation, 93.58 ohms differential Target 90 ohms 5 mil trace width, 16.5 mil seperation, 119.26 ohms differential Target 120 ohms
	Prepreg 1 - 2		
0.0350	Copper foil layer 2	Plane	
	Core 2 - 3		
0.0350	Copper foil layer 3	Signal	5.9 mil trace width, 53.69 ohms single ended Target 50 ohms 5 mil trace width, 13 mil seperation, 108.31 ohms differential Target 100 ohms 6 mil trace width, 10 mil seperation, 97.28 ohms differential Target 90 ohms 5 mil trace width, 22.9 mil seperation, 113.46 ohms differential Target 120 ohms
	Prepreg 3 - 4		
0.0350	Copper foil layer 4	Signal	5.9 mil trace width, 53.69 ohms single ended Target 50 ohms 5 mil trace width, 13 mil seperation, 108.31 ohms differential Target 100 ohms 6 mil trace width, 10 mil seperation, 97.28 ohms differential Target 90 ohms 5 mil trace width, 22.9 mil seperation, 113.46 ohms differential Target 120 ohms
	Core 4 - 5		
0.0350	Copper foil layer 5	Plane	
	Prepreg 5 - 6		
0.0350	Copper foil layer 6	Plane	
	Core 6 - 7		
0.0350	Copper foil layer 7	Signal	5.9 mil trace width, 53.69 ohms single ended Target 50 ohms 5 mil trace width, 13 mil seperation, 108.31 ohms differential Target 100 ohms 6 mil trace width, 10 mil seperation, 97.28 ohms differential Target 90 ohms 5 mil trace width, 22.9 mil seperation, 113.46 ohms differential Target 120 ohms
	Prepreg 7 - 8		
0.0350	Copper foil layer 8	Signal	5.9 mil trace width, 53.69 ohms single ended Target 50 ohms 5 mil trace width, 13 mil seperation, 108.31 ohms differential Target 100 ohms 6 mil trace width, 10 mil seperation, 97.28 ohms differential Target 90 ohms 5 mil trace width, 22.9 mil seperation, 113.46 ohms differential Target 120 ohms
	Core 8 - 9		
0.0350	Copper foil layer 9	Plane	
	Prepreg 9 - 10		
0.0175	Copper foil layer 10	Signal	6.5 mil trace width, 56.26 ohms single ended Target 50 ohms 5 mil trace width, 6.8 mil seperation, 103.74 ohms differential Target 100 ohms 6 mil trace width, 5.8 mil seperation, 93.58 ohms differential Target 90 ohms 5 mil trace width, 16.5 mil seperation, 119.26 ohms differential Target 120 ohms
0.0325	Copper plating layer 10		
1.7700	Total PCB thickness in mm		

Disclaimer: This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.